

PNZ108CL (PN108CL)

Silicon NPN Phototransistor

For optical control systems

Features

• High sensitivity : $I_{CE(L)} = 3.5 \text{ mA} \text{ (min.)}$ (at L = 500 lx)

• Wide directional sensitivity for easy use

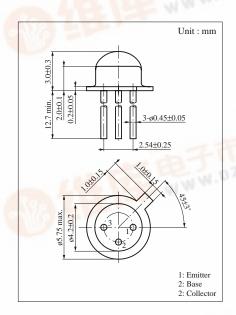
• Fast response : $t_r = 5 \mu s$ (typ.)

• Signal mixing capability using base pin

• Small size (low in height) package

■ Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Collector to emitter voltage	V _{CEO}	20	V
Collector to base voltage	V _{CBO}	30	V
Emitter to collector voltage	V _{ECO} 3		V
Emitter to base voltage	V_{EBO}	5	V
Collector current	I_{C}	20	mA
Collector power dissipation	P _C	100	mW
Operating ambient temperature	Topr	-25 to +85	°C
Storage temperature	T _{stg}	-30 to +100	°C

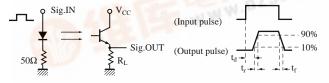


■ Electro-Optical Characteristics (Ta = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Dark current	I _{CEO}	$V_{CE} = 10V$		0.05	2	μΑ
Collector photo current	I _{CE(L)} *3	$V_{CE} = 10V, L = 500 lx^{*1}$	3.5	6		mA
Peak sensitivity wavelength	λ_{P}	$V_{CE} = 10V$		900		nm
Acceptance half angle	θ	Measured from the optical axis to the half power point		80	- 4	deg.
Rise time	t_r^{*2}	$V_{CC} = 10V, I_{CE(L)} = 5mA$		5		μs
Fall time	t_f^{*2}	$R_L = 100\Omega$		6	- 4	μs
Collector saturation voltage	V _{CE(sat)}	$I_{CE(L)} = 1 \text{mA}, L = 1000 \text{ lx}^{*1}$		0.3	0.6	V

^{*1} Measurements were made using a tungsten lamp (color temperature T = 2856K) as a light source.

^{*2} Switching time measurement circuit



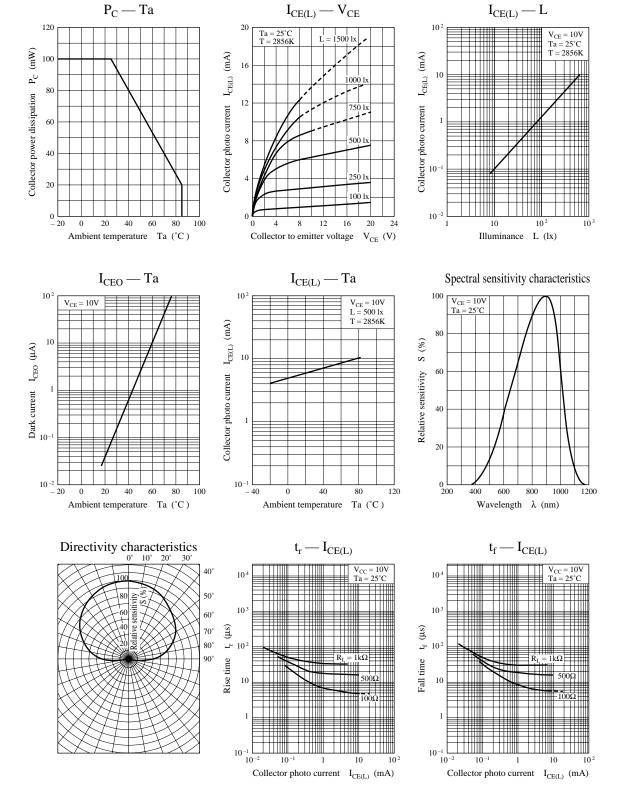
- t_d: Delay time
- t_r: Rise time (Time required for the collector photo current to increase from 10% to 90% of its final value)
- t_f: Fall time (Time required for the collector photo current to decrease from 90% to 10% of its initial value)

*3 I_{CE(L)} Classifications

(-)			
Class	Q	R	S
I _{CEIL} (mA)	3.5 to 6.0	5.0 to 9.1	> 7.5

ote) Difficult to guarantee compliance with moisture resistance standard (MIL-STD-202D).

Phototransistors PNZ108CL



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